



# SGM25062

## 6-Channel Load Switch with I<sup>2</sup>C Control

### GENERAL DESCRIPTION

The SGM25062 is CMOS based 6 channels integrated load switch with I<sup>2</sup>C Control.

Load switch 1 to 6 contains P-MOSFET that can operate over an input voltage of 1.2V to 5.5V and supports a maximum continuous current of 2A.

The SGM25062 is available in a Green WLCSP-1.55x1.55-16B package.

### FEATURES

- Load Switch 1 to 6 Input Voltage Operating Range: 1.2V to 5.5V
- Load Switch 1 to 6 Typical R<sub>DS(on)</sub>:  
52mΩ at V<sub>INX</sub> = 5V  
120mΩ at V<sub>INX</sub> = 1.8V
- V<sub>BIAS</sub> Input Voltage Operating Range: 1.5V to 5.5V
- I<sup>2</sup>C Serial Control to Program Each Load Switch On/Off
- Available in a Green WLCSP-1.55x1.55-16B Package

### APPLICATIONS

Battery-Powered Device  
Smartphones, Tablets  
Cameras, DVRs, STB and Camcorders

### TYPICAL APPLICATION

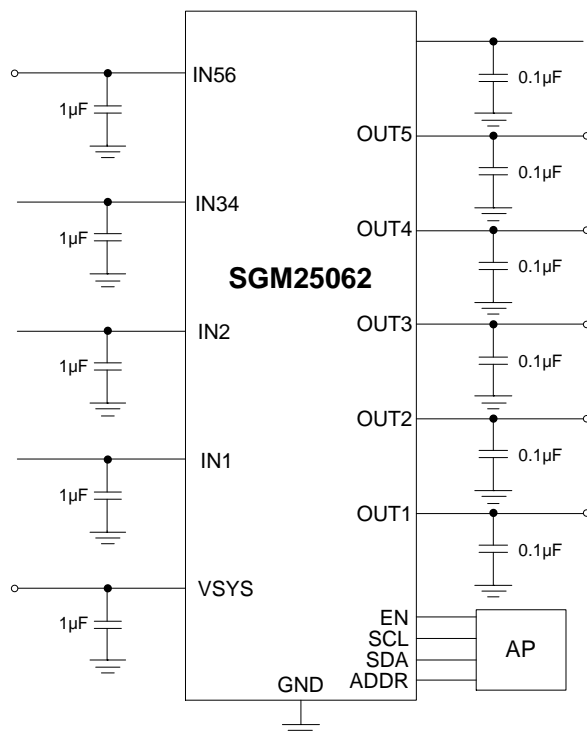


Figure 1. Typical Application Circuit

**PACKAGE/ORDERING INFORMATION**

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM25062	WLCSP-1.55x1.55-16B				

**MARKING INFORMATION**

NOTE: X = Date Code. XX = Date Code. XXXXX = Date Code, Trace Code and Vendor Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

**ABSOLUTE MAXIMUM RATINGS**

Power IN/OUT Pins Voltage (IN1, IN2, IN34, IN56, OUT1, OUT2, OUT3, OUT4, OUT5, OUT6, V<sub>SYS</sub>) ..... -0.3V to 6V  
 Other Pin Voltage ..... -0.3V to V<sub>VSYS</sub> + 0.3V  
 Each Load Switch Maximum Load Current..... 2A  
 Junction Temperature.....+150°C  
 Storage Temperature Range ..... -65°C to +150°C  
 Lead Temperature (Soldering, 10s).....+260°C  
 ESD

**RECOMMENDED OPERATING CONDITIONS**

Junction Temperature Range ..... -40°C to +125°C

**OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

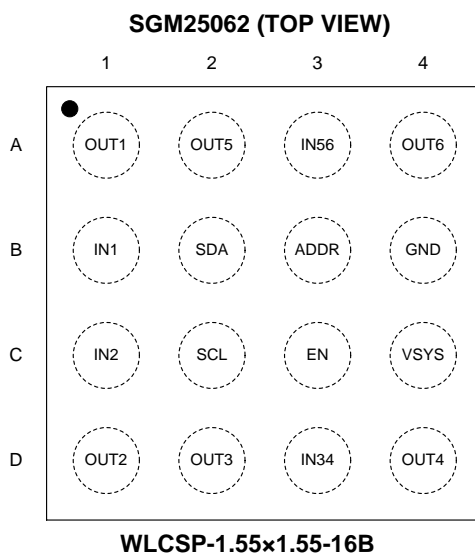
**ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

**DISCLAIMER**

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

## PIN CONFIGURATION



## PIN DESCRIPTION

PIN	NAME	FUNCTION
A1	OUT1	Load Switch 1 Output.
A2	OUT5	Load Switch 5 Output.
A3	IN56	Load Switch 5 and 6 Supply Input.
A4	OUT6	Load Switch 6 Output.
B1	IN1	Load Switch 1 Supply Input.
B2	SDA	I <sup>2</sup> C Interface.
B3	ADDR	I <sup>2</sup> C Address Set Pin.
B4	GND	Ground Pin.
C1	IN2	Load Switch 2 Supply Input.
C2	SCL	I <sup>2</sup> C Interface.
C3	EN	Load Switch Output Enable (Active High). <a href="#">Device will reset all registers to default value when EN pin is low.</a>
C4	VSYS	System Supply Input.
D1	OUT2	Load Switch 2 Output.
D2	OUT3	Load Switch 3 Output.
D3	IN34	Load Switch 3 and 4 Supply Input.
D4	OUT4	Load Switch 4 Output.

**ELECTRICAL CHARACTERISTICS**

(C<sub>VSYS</sub> = 1μF, T<sub>A</sub> = -40°C to +85°C, typical values are at T<sub>A</sub> = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
VSYS Voltage Range	V <sub>VSYS</sub>		1.5		5.5	V
VSYS Current	I <sub>Q_ON</sub>	Active mode: V <sub>EN</sub> = V <sub>VSYS</sub> and Enable chip by I <sup>2</sup> C			1	μA
	I <sub>Q_OFF</sub>	V <sub>EN</sub> = 0V, and V <sub>ADDR</sub> = V <sub>SCL</sub> = V <sub>SDA</sub> = 0 or V <sub>ADDR</sub> = V <sub>SCL</sub> = V <sub>SDA</sub> = V <sub>VSYS</sub>			1	μA
EN Pin Pull Down Resistance	R <sub>EN</sub>		8	12		MΩ
EN Leakage	I <sub>EN</sub>	V <sub>EN</sub> = 5V			0.6	μA
EN Input Voltage High	V <sub>ENH</sub>		1.2			V
EN Input Voltage Low	V <sub>ENL</sub>				0.4	V
SCL/SDA Input Voltage High	V <sub>I2CH</sub>		1.2			V
SCL/SDA Input Voltage Low	V <sub>I2CL</sub>				0.4	V
SDA Logic Low Output	V <sub>OL</sub>	3mA Sink			0.4	V
SCL/SDA Input Current	I <sub>I2C</sub>	EN = 0 and V <sub>SCL</sub> = V <sub>SDA</sub> = V <sub>VSYS</sub> or V <sub>SCL</sub> = V <sub>SDA</sub> = 0		0.1		μA
SCL Clock Frequency	F <sub>SCL</sub>				400	kHz

(V<sub>IN1</sub> = V<sub>IN2</sub> = V<sub>IN34</sub> = V<sub>IN56</sub> = 1.2V to 5.5V, T<sub>A</sub> = -40°C to +85°C, typical values are at V<sub>INX</sub> = 3.3V and T<sub>A</sub> = +25°C. V<sub>VSYS</sub> = 1.5V to 5.5V, unless otherwise noted.)

PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>Basic Operation</b>						
Input Voltage	V <sub>INX</sub>		1.2		5.5	V
Off Supply Current of One Channel LS T <sub>A</sub> = +25°C	I <sub>QX(OFF)</sub>	V <sub>EN</sub> = GND, V <sub>OUTX</sub> floating, V <sub>INX</sub> = 5V			0.5	μA
		V <sub>EN</sub> = GND, V <sub>OUTX</sub> floating, V <sub>INX</sub> = 3.3V			0.5	
		V <sub>EN</sub> = GND, V <sub>OUTX</sub> floating, V <sub>INX</sub> = 1.8V			0.5	
Shutdown Current of One Channel LS T <sub>A</sub> = +25°C	I <sub>SD</sub>	V <sub>EN</sub> = GND, V <sub>OUTX</sub> = 0V, V <sub>INX</sub> = 5V			0.5	μA
		V <sub>EN</sub> = GND, V <sub>OUTX</sub> = 0V, V <sub>INX</sub> = 3.3V			0.5	
		V <sub>EN</sub> = GND, V <sub>OUTX</sub> = 0V, V <sub>INX</sub> = 1.8V			0.5	
Quiescent Current of One channel LS T <sub>A</sub> = +25°C	I <sub>Q</sub>	V <sub>EN</sub> = V <sub>VSYS</sub> , I <sub>OUTX</sub> = 0mA, V <sub>INX</sub> = 5V			0.5	μA
		V <sub>EN</sub> = V <sub>VSYS</sub> , I <sub>OUTX</sub> = 0mA, V <sub>INX</sub> = 3.3V			0.5	
		V <sub>EN</sub> = V <sub>VSYS</sub> , I <sub>OUTX</sub> = 0mA, V <sub>INX</sub> = 1.8V			0.5	
Quiescent Current of One channel LS T <sub>A</sub> = +25°C (RCB on)	I <sub>Q_R</sub>	V <sub>EN</sub> = V <sub>VSYS</sub> , I <sub>OUTX</sub> = 0mA, V <sub>INX</sub> = 5V		1.5	4	μA
		V <sub>EN</sub> = V <sub>VSYS</sub> , I <sub>OUTX</sub> = 0mA, V <sub>INX</sub> = 3.3V		0.9	2.5	
		V <sub>EN</sub> = V <sub>VSYS</sub> , I <sub>OUTX</sub> = 0mA, V <sub>INX</sub> = 1.8V		0.3	0.8	
On-Resistance T <sub>A</sub> = +25°C	R <sub>ON</sub>	V <sub>INX</sub> = 5V, I <sub>OUTX</sub> = 200mA		52	70	mΩ
		V <sub>INX</sub> = 3.3V, I <sub>OUTX</sub> = 200mA		66	85	
		V <sub>INX</sub> = 1.8V, I <sub>OUTX</sub> = 200mA		120	150	
OUT Pin Discharge Resistance (default)	R <sub>PD</sub>	V <sub>INX</sub> = 3.3V, EN = 0V, V <sub>OUTX</sub> = 1V, T <sub>A</sub> = +25°C		66	100	Ω
<b>True Reverse Current Blocking</b>						
RCB Protection Trip Point	V <sub>T_RCB</sub>	V <sub>OUT</sub> - V <sub>INX</sub>		60		mV
RCB Protection Release Trip Point	V <sub>R_RCB</sub>	V <sub>INX</sub> - V <sub>OUT</sub>		65		mV
RCB Hysteresis				125		mV
V <sub>OUT</sub> Shutdown Current	I <sub>SD_OUT</sub>	LSW off, V <sub>OUT</sub> = 5.0V, V <sub>IN</sub> = Short to GND		1.4		μA
RCB Response Time when Device On <sup>(1)</sup>	T <sub>RCB_ON</sub>	V <sub>OUT</sub> - V <sub>IN</sub> = 200mV, V <sub>ON</sub> = High		3		μs
RCB Response Time Device Off <sup>(1)</sup>	T <sub>RCB_OFF</sub>	V <sub>IN</sub> - V <sub>OUT</sub> = 200mV, V <sub>ON</sub> = High		4		μs

**ELECTRICAL CHARACTERISTICS (continued)**

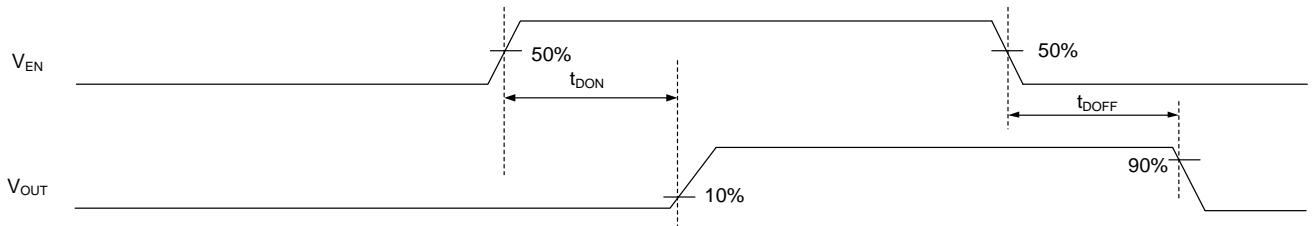
(V<sub>IN1</sub> = V<sub>IN2</sub> = V<sub>IN34</sub> = V<sub>IN56</sub> = 1.2V to 5.5V, T<sub>A</sub> = -40°C to +85°C, typical values are at V<sub>INX</sub> = 3.3V and T<sub>A</sub> = +25°C. V<sub>VSYS</sub> = 1.5V to 5.5V, unless otherwise noted.)

PARAMETERS	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>Dynamic Characteristics: See Definitions Below (Default)</b>						
Turn-On Delay <sup>(1,2)</sup>	t <sub>DON</sub>	V <sub>INX</sub> = 3.3V, R <sub>L</sub> = 150Ω, C <sub>L</sub> = 0.1μF		270		μs
V <sub>OUT</sub> Rise Time <sup>(1,2)</sup>	t <sub>R</sub>			340		
Turn-On Delay <sup>(1,2)</sup>	t <sub>DON</sub>	V <sub>INX</sub> = 3.3V, R <sub>L</sub> = 500Ω, C <sub>L</sub> = 0.1μF		250		μs
V <sub>OUT</sub> Rise Time <sup>(1,2)</sup>	t <sub>R</sub>			320		
Turn-Off Delay <sup>(1,2)</sup>	t <sub>DOFF</sub>	V <sub>INX</sub> = 3.3V, R <sub>L</sub> = 150Ω, C <sub>L</sub> = 0.1μF		0.8		μs
V <sub>OUT</sub> Fall Time <sup>(1,2)</sup>	t <sub>F</sub>			10.5		
Turn-Off Delay <sup>(1,2)</sup>	t <sub>DOFF</sub>	V <sub>INX</sub> = 3.3V, R <sub>L</sub> = 500Ω, C <sub>L</sub> = 0.1μF		1.1		μs
V <sub>OUT</sub> Fall Time <sup>(1,2)</sup>	t <sub>F</sub>			14		

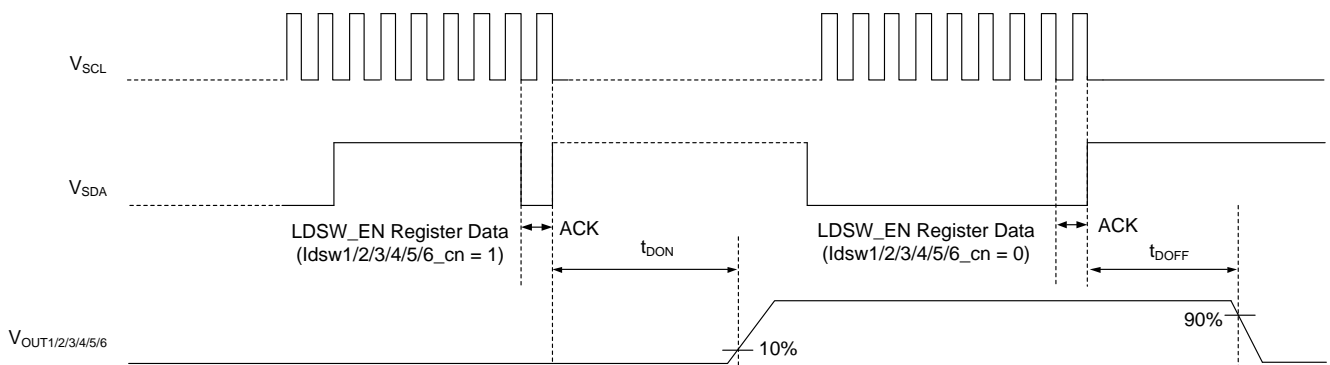
**NOTES:**

1. This parameter is guaranteed by design and characterization; not production tested.
2. t<sub>DON</sub>/t<sub>DOFF</sub>/t<sub>R</sub>/t<sub>F</sub> are defined in Figure 2.

**TIMING DIAGRAM**



**EN Pin Control V<sub>OUT</sub> When LDSW\_EN Register Had Already Enabled**



**LDSW\_EN register Control V<sub>OUT</sub> when EN Pin had already set to high level**



**Figure 2.**

### I<sup>2</sup>C MODE TIMING

SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
F <sub>SCL</sub>	SCL Clock Frequency.	0	-	400	kHz
t <sub>BUF</sub>	Bus Free Time Between a STOP and START Condition.	1.3	-	-	μs
t <sub>HD:STA</sub>	Hold Time (Repeated) START Condition.	0.6	-	-	μs
t <sub>LOW</sub>	Low Period of SCL Clock.	1.3	-	-	μs
t <sub>HIGH</sub>	HIGH Period of SCL Clock.	0.6	-	-	μs
t <sub>SU:STA</sub>	Setup Time for a Repeated START Condition.	0.6	-	-	μs
t <sub>HD:DAT</sub>	Data Hold Time.	-	-	0.9	μs
t <sub>SU:DAT</sub>	Data Setup Time.	100	-	-	ns
t <sub>R</sub>	Data Hold Time2.	20+0.1Cb <sup>(1)</sup>	-	300	ns
t <sub>F</sub>	Data Hold Time2.	20+0.1Cb	-	300	ns
t <sub>SU:STO</sub>	Setup Time for STOP Condition.	0.6	-	-	μs

1: C<sub>b</sub> = total capacitance of one bus line in PF.

### I<sup>2</sup>C MODE TIMING DIAGRAM

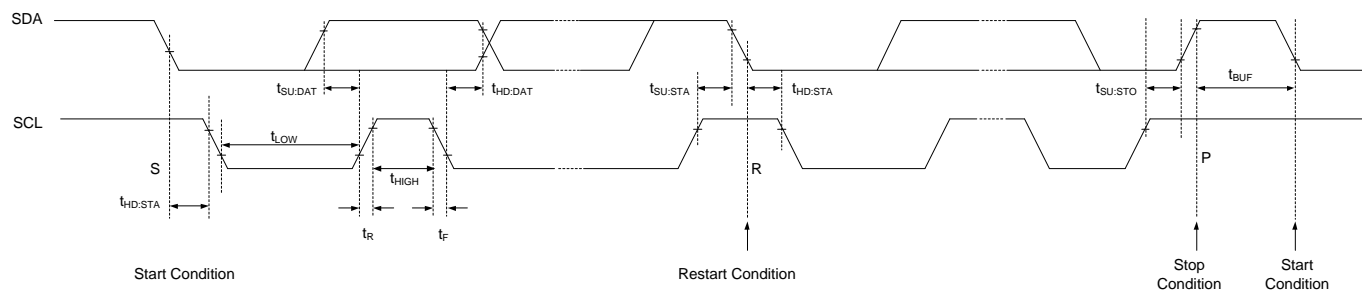
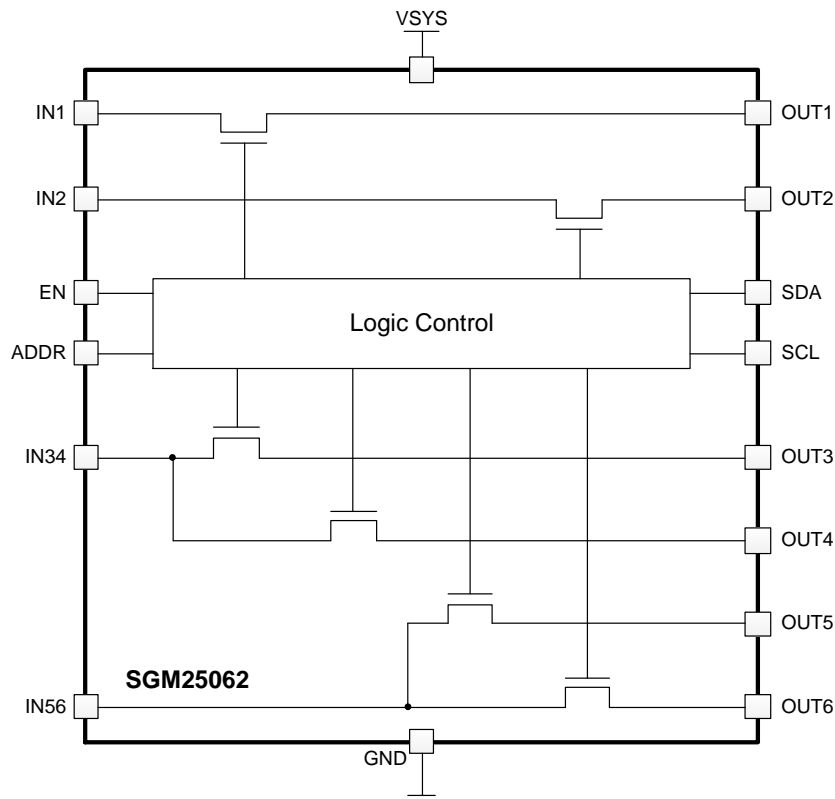


Figure 3. I<sup>2</sup>C Mode Timing Diagram

**FUNCTIONAL BLOCK DIAGRAM**



Note: The OUT<sub>x</sub> port has a fast turn-off discharge circuit. This function can be turned off by I<sup>2</sup>C command.

**Figure 4. Block Diagram**

**FUNCTIONAL DESCRIPTION**

SGM25062 has 6 channels load switch. Load switch 1 to 6 are using P-MOSFET.

**Start-Up**

The SGM25062 LDSW's can be enabled two ways using the I<sup>2</sup>C register bits if EN is high.

1. Setting LDSWX\_SEQ = 000 in 0x05 (LDSW12\_SEQ) or 0x06 (LDSW34\_SEQ) or 0x07 (LDSW56\_SEQ) and the LDSWX\_EN assigned to the LDSW in register, ENABLE to 1.
2. Setting LDSWX\_SEQ > 000 in registers and then set seq\_ctrl[1:0] = 2'b01 in SEQ\_CTR register.

Power-up and shut down of each regulator can be controlled by an I<sup>2</sup>C register. It can be set at the registers ldswx\_seq[2:0] (x = 1 to 7) respectively. ldswx\_en is an internal signal to enable one of regulators, if ldswx\_seq[2:0] set to '000', that LDSWX channel can be controlled directly by a bit specified in register LDSW\_EN.

3. Automatic power-up/down sequence control.

SGM25062 has seven SLOTS to which each regulator can be assigned.

They are started by seq\_ctrl[1:0] signal. when seq\_ctrl[1:0] is set '01'. Internal counter seq\_cnt[2:0] starts increments from 0 ("000") to 7 ("111"). When seq\_ctrl[1:0] is set '10', seq\_cnt[2:0] decrements from 7 ("111") to 0 ("000"). Regulators assigned to one of SLOTS starts power-up or power-down.

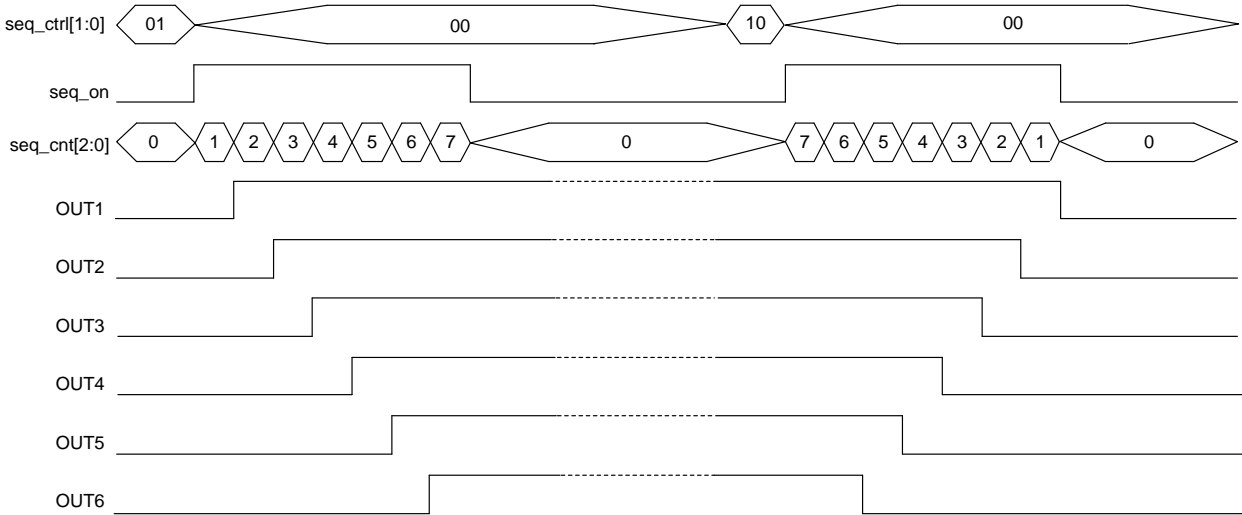
The seq\_cnt[2:0] matches the SLOT number, when seq\_cnt[2:0] = 000, it indicates that sequencing has completed or not started.

**FUNCTIONAL DESCRIPTION (continued)**

Internal logic signal seq\_on = 1 indicates that sequencing is executing and somewhere between the start of slot 1 and the end of slot 7, seq\_on = 0, it indicates that has completed or not started.

**4. EN pin control**

When EN pin is in low level, the IC is shut down, all internal circuits are off, and all the parts draw very little current. In this state, all the registers will be reset to their default value, and I<sup>2</sup>C cannot be written to or read.



Example of power-up in the case of OUT1–OUT6 are assigned to SLOT1-SLOT7 respectively.

Example of shutdown in the case of OUT1–OUT6 are assigned to SLOT1-SLOT7 respectively.

**Input and output Capacitor**

To limit the voltage drop on the input supply caused by transient inrush current when the switch turns on into a discharged load capacitor or short-circuit, a capacitor must be placed between the V<sub>INX</sub> and GND pins. A 1µF ceramic capacitor, C<sub>INX</sub>, placed close to the pins is usually sufficient. Higher-value C<sub>INX</sub> can be used to reduce the voltage drop in higher-current applications.

A 0.1µF capacitor, C<sub>OUTX</sub>, should be placed between the V<sub>OUTX</sub> and GND pins. This capacitor prevents parasitic board inductance from forcing V<sub>OUTX</sub> below GND when the switch is on. C<sub>INX</sub> greater than C<sub>OUTX</sub> is highly recommended. C<sub>OUTX</sub> greater than C<sub>IN</sub> can cause V<sub>OUTX</sub> to exceed V<sub>INX</sub> when the system supply is removed. This could result in current flow through the body diode from V<sub>OUTX</sub> to V<sub>INX</sub>.

Recommended C<sub>VSYS</sub> = 1.0µF or greater.

**Auto Discharging**

For each channel, when shut down the output, the auto-discharging circuit will be turned on to discharge the electric charge on output capacitor, and decrease the voltage of output pin in very short time. The auto-discharging function is optional. Set related bits to select output discharge function for Discharge Resistor (LDSW\_DIS Register), “0”: Disable. “1”: Enable.



**FUNCTIONAL DESCRIPTION (continued)**

**RCB Function**

SGM25062 has a true reverse current function that obstructs unwanted reverse current from OUTx to INx during both ON and OFF states. The RCB function can be set by I<sup>2</sup>C instruction (LDSW\_RCB register).

LSWx State	ldswx_rcb	RCB Function
OFF	0	Y
OFF	1	Y
ON	0	N
ON	1	Y

NOTES:

- 1. x is 1~6;
- 2. LSWx state is controlled by EN pin or LDSW\_EN Register.

**Serial Port Interface (I<sup>2</sup>C)**

**Bus Interface**

Baseband Processor can transmit data with SGM25062 each other through SDA and SCL port. SDA and SCL composite bus interface, and a pull-up resistor to the power supply should be connected.

**Data Validity**

When the SCL signal is high, the data of SDA port is valid and stable. Only when the SCL signal is low, the level on the SDA port can be changed.

**Start (Re-start) and Stop Working Conditions**

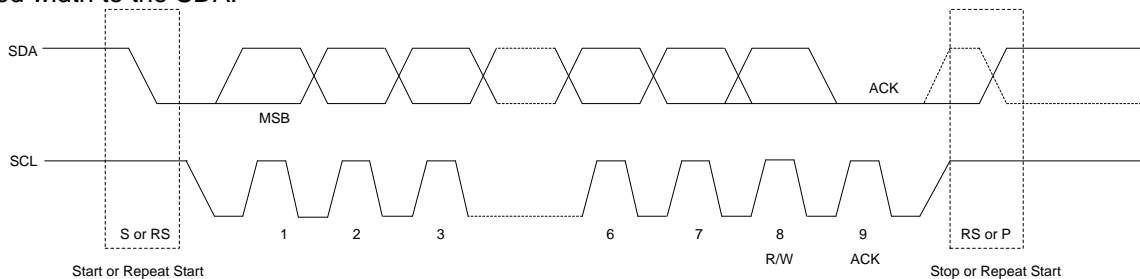
When the SCL signal is high, SDA signal from high to low represents start or re-start working conditions, while the SCL signal is high, SDA signal from low to high represents stop working conditions.

**Byte format**

Each byte of data line contains 8 bits, which contains an acknowledge bit. The first data is transmitted MSB.

**Acknowledge**

During the writing mode, SGM25062 will send a low level response signal with one period width to the SDA port. During the reading mode, SGM25062 will not send response signal and the host will send a high response signal one period width to the SDA.



**I<sup>2</sup>C Write Mode**

NOTE: ACK = Acknowledge

MSB = Most Significant Bit

S = Start Conditions

RS = Restart Conditions

P = Stop Conditions

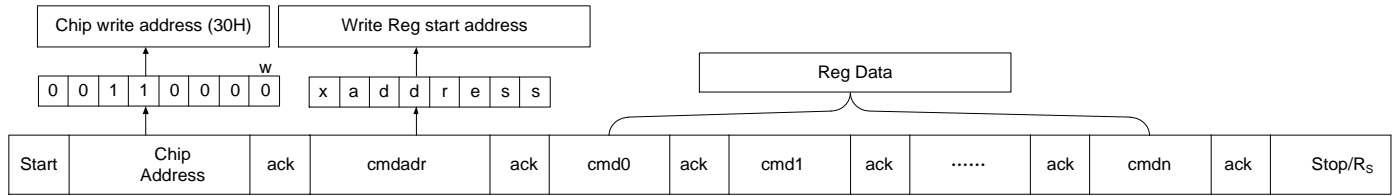
Fastest Transmission Speed = 400kHz

Restart: SDA-level turnover as expressed by the dashed line waveform

**7bit Chip Address:** 0011000b (ADDR connect to GND), 0011001b (ADDR connect to VSYS)

**FUNCTIONAL DESCRIPTION (continued)**

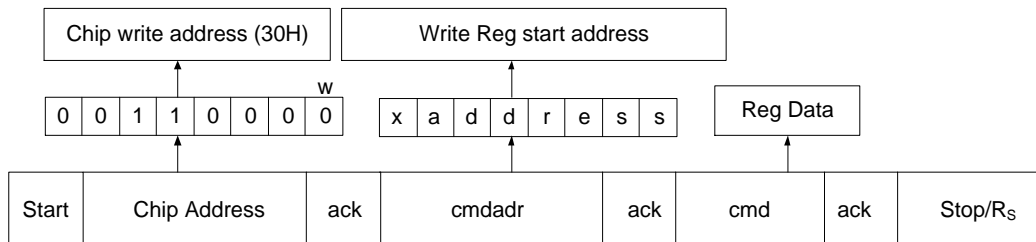
**I<sup>2</sup>C Writing Command Register Interface Protocol (continuous):**



**Figure 5. I<sup>2</sup>C Writing Command Register (continuous)**

- Start = Start Conditions
- Chip address = Write register address = 0011000+0(w)b
- ack = Acknowledge
- Write Reg start address byte = cmdadr (x + REG's 7bit address)
- ack = Acknowledge
- Reg data 0 = cmd0 (Command data0)
- ack = Acknowledge
- .....
- Reg data n = cmdn (Command datan)
- ack = Acknowledge
- Stop/Rs = Stop Condition/Restart Condition

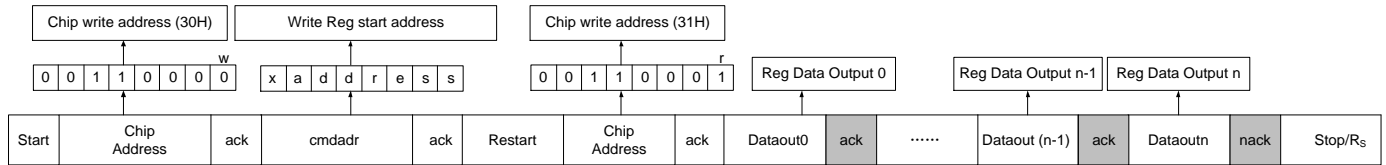
**I<sup>2</sup>C Writing Command Register Interface Protocol (single):**



- Start = Start Conditions
- Chip address = Write register address = 0011000+0(w)b
- ack = Acknowledge
- Write Reg start address byte = cmdadr (x + REG's 7bit address)
- ack = Acknowledge
- Reg data = cmd (Command data)
- ack = Acknowledge
- Stop/Rs = Stop Condition/Restart Condition

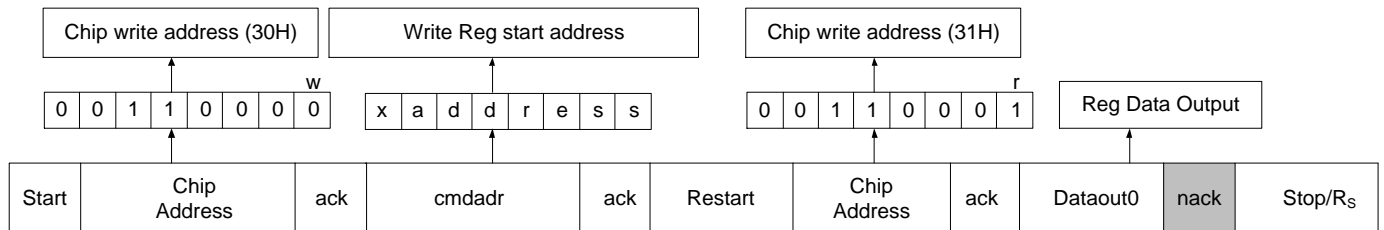
**DETAILED DESCRIPTION (continued)**

**I<sup>2</sup>C Reading Command Register Interface Protocol (continuous)**



- Start = Start Conditions
- Chip address = Write register address = 0011000+0(w)b
- ack = Acknowledge
- Write Reg start address byte = cmdadr (x+ REG's 7bit address)
- ack = Acknowledge from SGM25062
- Restart = Restart condition
- Chip address Read register address=0011000+1(r)b
- ack = Acknowledge from SGM25062
- Dataout0 = Register data output 0
- ack = Acknowledge from Host
- .....
- Dataoutn = Register data output n
- nack = No Acknowledge from Host
- Stop/R<sub>s</sub> = Stop Condition/Restart Condition

**I<sup>2</sup>C Reading Command Register Interface Protocol (Single)**



- Start = Start Conditions
- Chip address = Write register address = 0011000+0(w)b
- ack = Acknowledge from SGM25062
- Write Reg start address byte = cmdadr (x + REG's 7bit address)
- ack = Acknowledge from SGM25062
- Restart = Restart condition
- Chip address Read register address = 0011000+1(r)b
- ack = Acknowledge from SGM25062
- Dataout = Register data output
- nack = No Acknowledge from Host
- Stop/R<sub>s</sub> = Stop Condition/Restart Condition

**DETAILED DESCRIPTION (continued)**

**Register Map**

Addr	Name	RST	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0x00	CHIPID	0x30	001100						chip_id[1:0]	
0x01	VERID	0x00	000000						ver_id[1:0]	
0x02	LDSW_EN	0x00	0	0	ldsw6_en	ldsw5_en	ldsw4_en	ldsw3_en	ldsw2_en	ldsw1_en
0x03	LDSW_DIS	0x3F	0	0	ldsw6_dis	ldsw5_dis	ldsw4_dis	ldsw3_dis	ldsw2_dis	ldsw1_dis
0x04	LDSW_TR0	0x00	0	0	ldsw6_tr0	ldsw5_tr0	ldsw4_tr0	ldsw3_tr0	ldsw2_tr0	ldsw1_tr0
0x05	LDSW12_SEQ	0x00	0	0	ldsw2_seq[2:0]		ldsw1_seq[2:0]			
0x06	LDSW34_SEQ	0x00	0	0	ldsw4_seq[2:0]		ldsw3_seq[2:0]			
0x07	LDSW56_SEQ	0x00	0	0	ldsw6_seq[2:0]		ldsw5_seq[2:0]			
0x08	SEQ_CTR	0x00	seq_speed[1:0]		seq_ctrl[1:0]		seq_on	seq_cnt[2:0]		
0x09	LDSW_TR1	0x00	0	0	ldsw6_tr1	ldsw5_tr1	ldsw4_tr1	ldsw3_tr1	ldsw2_tr1	ldsw1_tr1
0x0A	LDSW_RCB	0x00	0	0	ldsw6_rcb	ldsw5_rcb	ldsw4_rcb	ldsw3_rcb	ldsw2_rcb	ldsw1_rcb
0x0B	LDSW_STA	0x00	0	0	ldsw6_sta	ldsw5_sta	ldsw4_sta	ldsw3_sta	ldsw2_sta	ldsw1_sta
0x69	SOFT_RST_CTR	0x00	Write B0H to this register can reset all the registers to their default value							

NOTE: Rev.- Reserve, keep “0”.

**Register Description**

**0x00 CHIPID Register**----Indicates the product ID with revision. Default = 0x30

chip\_id[1:0] Indicates the product ID with revision. Read only.

**0x01 VERID Register**----Indicates the device ID with revision. Default = 0x00

ver\_id[1:0] Indicates the device ID with revision. Read only.

**0x02 LDSW\_EN Register**----LDSWs enable control register. Default = 0x00

Load Switch enable control register by I<sup>2</sup>C while the register value of ldswx\_seq[2:0] are set to be default “000”. This register can be written to enable or disable the corresponding LDSW regulator.

Bit	Name	Default	Type	Description
7	Rev.	0	R	Reverse
6	Rev.	0	R	Reverse
5	ldsw6_en	0	R/W	LDSW6 enable control: 0b: Disable 1b: Enable
4	ldsw5_en	0	R/W	LDSW5 enable control: 0b: Disable 1b: Enable
3	ldsw4_en	0	R/W	LDSW4 enable control: 0b: Disable 1b: Enable
2	ldsw3_en	0	R/W	LDSW3 enable control : 0b:Disable 1b: Enable
1	ldsw2_en	0	R/W	LDSW2 enable control: 0b: Disable 1b: Enable
0	ldsw1_en	0	R/W	LDSW1 enable control: 0b: Disable 1b: Enable

**DETAILED DESCRIPTION (continued)****0x03 LDSW\_DIS Register----Discharge Resistor Selection. Default = 0x3F**

Each LDSW regulators output discharge resistor enable control.

Bit	Name	Default	Type	Description
7	Rev.	0	R	Reversed
6	Rev.	0	R	Reversed
5	ldsw6_dis	1	R/W	LDSW6 Discharge Enabled/Disabled control : 0b:Disable Pull down will not be activated when LDSW6 is disabled by any event 1b: Enable Pull down will be activated when LDSW6 is disabled by EN going low or ldsw6_en = 0 or a Sequenced shutdown
4	ldsw5_dis	1	R/W	LDSW5 Discharge Enabled/Disabled control: 0b:Disable Pull down will not be activated when LDSW5 is disabled by any event 1b: Enable Pull down will be activated when LDSW5 is disabled by EN going low or ldsw5_en = 0 or a Sequenced shutdown
3	ldsw4_dis	1	R/W	LDSW4 Discharge Enabled/Disabled control: 0b:Disable Pull down will not be activated when LDSW4 is disabled by any event 1b: Enable Pull down will be activated when LDSW4 is disabled by EN going low or ldsw4_en = 0 or a Sequenced shutdown
2	ldsw3_dis	1	R/W	LDSW3 Discharge Enabled/Disabled control: 0b:Disable Pull down will not be activated when LDSW3 is disabled by any event 1b: Enable Pull down will be activated when LDSW3 is disabled by EN going low or ldsw3_en = 0 or a Sequenced shutdown
1	ldsw2_dis	1	R/W	LDSW2 Discharge Enabled/Disabled control: 0b:Disable Pull down will not be activated when LDSW2 is disabled by any event 1b: Enable Pull down will be activated when LDSW2 is disabled by EN going low or ldsw2_en = 0 or a Sequenced shutdown
0	ldsw1_dis	1	R/W	LDSW1 Discharge Enabled/Disabled control : 0b:Disable Pull down will not be activated when LDSW1 is disabled by any event 1b: Enable Pull down will be activated when LDSW1 is disabled by EN going low or ldsw1_en = 0 or a Sequenced shutdown

**DETAILED DESCRIPTION (continued)****0x04/09H LDSW\_TR0/1 Register----Load Switch output voltage rise timing Selection. Default = 0x00** $V_{INX} = 3.3V$ ,  $R_L = 150\Omega$ ,  $C_L = 0.1\mu F$ 

Bit	Name	Default	Type	Description
7	Rev.	00/00	R	Reversed
6	Rev.	00/00	R	Reversed
5	ldsw6_tr1 ldsw6_tr0	00	R/W	LDSW6 output voltage (from 10% to 90%) rise time setting control: 00b: 340 $\mu$ s 01b: 32 $\mu$ s 10b: 150 $\mu$ s 11b: 1000 $\mu$ s
4	ldsw5_tr1 ldsw5_tr0	00	R/W	LDSW5 output voltage (from 10% to 90%) rise time setting control: 00b: 340 $\mu$ s 01b: 32 $\mu$ s 10b: 150 $\mu$ s 11b: 1000 $\mu$ s
3	ldsw4_tr1 ldsw4_tr0	00	R/W	LDSW4 output voltage (from 10% to 90%) rise time setting control: 00b: 340 $\mu$ s 01b: 32 $\mu$ s 10b: 150 $\mu$ s 11b: 1000 $\mu$ s
2	ldsw3_tr1 ldsw3_tr0	00	R/W	LDSW3 output voltage (from 10% to 90%) rise time setting control: 00b: 340 $\mu$ s 01b: 32 $\mu$ s 10b: 150 $\mu$ s 11b: 1000 $\mu$ s
1	ldsw2_tr1 ldsw2_tr0	00	R/W	LDSW2 output voltage (from 10% to 90%) rise time setting control: 00b: 340 $\mu$ s 01b: 32 $\mu$ s 10b: 150 $\mu$ s 11b: 1000 $\mu$ s
0	ldsw1_tr1 ldsw1_tr0	00	R/W	LDSW1 output voltage (from 10% to 90%) rise time setting control: 00b: 340 $\mu$ s 01b: 32 $\mu$ s 10b: 150 $\mu$ s 11b: 1000 $\mu$ s

**0x05 LDSW12\_SEQ Register----Power sequence setting register. Default = 0x00**

Power sequence setting register. There are 7 time slots defined as following table. The power-up sequence is start from slot1 to slot7, and shut down start from slot7 to slot1. Power-up and shut down of each LDSW1/2 regulator can be set at any one of the slots.

Bit	Name	Default	Type	Description
7:6	Rev.	00	R	Reserved
5:3	ldsw2_seq[2:0]	000	R/W	<b>VOUT2</b> 000: Controlled by I <sup>2</sup> C register lds2_en 001: Slot1 010: Slot2 011: Slot3 100: Slot4 101: Slot5 110: Slot6 111: Slot7
2:0	ldsw1_seq[2:0]	000	R/W	<b>VOUT1</b> 000: Controlled by I <sup>2</sup> C register lds1_en 001: Slot1 010: Slot2 011: Slot3 100: Slot4 101: Slot5 110: Slot6 111: Slot7

**DETAILED DESCRIPTION (continued)**

**0x06 LDSW34\_SEQ Register----Power sequence setting register. Default = 0x00**

Power sequence setting register. there are 7 time slots defined as following table. The power-up sequence is start from slot1 to slot7, and shut down start from slot7 to slot1. Power-up and shut down of each LDSW3/4 regulator can be set at any one of the slots.

Bit	Name	Default	Type	Description
7:6	Rev.	00	R	Reserved
5:3	ldsw4_seq[2:0]	000	R/W	<b>VOUT4</b> 000: Controlled by I <sup>2</sup> C register ldsw4_en 001: Slot1 010: Slot2 011: Slot3 100: Slot4 101: Slot5 110: Slot6 111: Slot7
2:0	ldsw3_seq[2:0]	000	R/W	<b>VOUT3</b> 000: Controlled by I <sup>2</sup> C register ldsw3_en 001: Slot1 010: Slot2 011: Slot3 100: Slot4 101: Slot5 110: Slot6 111: Slot7

**0x07 LDSW56\_SEQ Register----Power sequence setting register. Default = 0x00**

Power sequence setting register. there are 7 time slots defined as following table. The power-up sequence is start from slot1 to slot7, and shut down start from slot7 to slot1. Power-up and shut down of each LDSW5/6 regulator can be set at any one of the slots.

Bit	Name	Default	Type	Description
7:6	Rev.	00	R	Reserved
5:3	ldsw6_seq[2:0]	000	R/W	<b>VOUT6</b> 000: Controlled by I <sup>2</sup> C register ldsw6_en 001: Slot1 010: Slot2 011: Slot3 100: Slot4 101: Slot5 110: Slot6 111: Slot7
2:0	ldsw5_seq[2:0]	000	R/W	<b>VOUT5</b> 000: Controlled by I <sup>2</sup> C register ldsw5_en 001: Slot1 010: Slot2 011: Slot3 100: Slot4 101: Slot5 110: Slot6 111: Slot7

**DETAILED DESCRIPTION (continued)****0x08 SEQ\_CTR Register----Power sequence setting and status register. Default = 0x00**

Bit	Name	Default	Type	Description
7:6	seq_speed[1:0]	00	R/W	Define the slot period as following: 00: 0.5ms 01: 1.0ms 10: 1.5ms 11: 2.0ms
5:4	seq_ctrl[1:0]	00	W/C	Enables power-up or shut down of SEQ: 00: Default 01: Starts an LDSW power up sequence 10: Starts an LDSW shutdown sequence 11: Bit configuration is ignored Note: The bits will always clear immediately when written to and always read back 00.
3	seq_on	0	R	Indicates the activation signal of SEQ. 0b: Indicates that the sequencing is not in process 1b: Indicates that the sequencing is executing and somewhere between the start of slot 1 and the end of slot 7. The bit remains a 1 until slot 7 has completed at start-up or slot 1 has finished at shutdown, regardless of what slots are used.
2:0	seq_cnt[2:0]	000	R	Indicates the slot number of SEQ at the moment: 000: Sequencing has completed or not started. 001: Indicates was in slot 1 during register read 010: Indicates was in slot 2 during register read 011: Indicates was in slot 3 during register read 100: Indicates was in slot 4 during register read 101: Indicates was in slot 5 during register read 110: Indicates was in slot 6 during register read 111: Indicates was in slot 7 during register read



**DETAILED DESCRIPTION (continued)****0x0A LDSW\_RCB Register----RCB Function Selection. Default = 0x00**

This register enables the function blocking the current of load switch when the output voltage is higher than input.

Bit	Name	Default	Type	Description
7	Rev.	0	R	Reserved
6	Rev.	0	R	Reserved
5	ldsw6_rcb	0	R/W	LDSW6 reverse current blocking function: 0b:Disable 1b: Enable
4	ldsw5_rcb	0	R/W	LDSW5 reverse current blocking function: 0b:Disable 1b: Enable
3	ldsw4_rcb	0	R/W	LDSW4 reverse current blocking function: 0b:Disable 1b: Enable
2	ldsw3_rcb	0	R/W	LDSW3 reverse current blocking function: 0b:Disable 1b: Enable
1	ldsw2_rcb	0	R/W	LDSW2 reverse current blocking function: 0b:Disable 1b: Enable
0	ldsw1_rcb	0	R/W	LDSW1 reverse current blocking function: 0b:Disable 1b: Enable

**0x0B LDSW\_STA Register----LDSW Status Register. Default = 0x00**

Bit	Name	Default	Type	Description
7	Rev.	0	R	Reserved
6	Rev.	0	R	Reserved
5	ldsw6_sta	0	R	LDSW6 Status Bit: 0b:Turn off Status 1b: Turn on Status
4	ldsw5_sta	0	R	LDSW5 Status Bit: 0b:Turn off Status 1b: Turn on Status
3	ldsw4_sta	0	R	LDSW4 Status Bit: 0b:Turn off Status 1b: Turn on Status
2	ldsw3_sta	0	R	LDSW3 Status Bit: 0b:Turn off Status 1b: Turn on Status
1	ldsw2_sta	0	R	LDSW2 Status Bit: 0b:Turn off Status 1b: Turn on Status
0	ldsw1_sta	0	R	LDSW1 Status Bit: 0b:Turn off Status 1b: Turn on Status

**0x69 SOFTRST\_CTR Register----Software Reset Signal. Default = 0x00**

Write B0H to this register will be produced a reset signal, this signal will reset all the registers to the default value.

Bit	Name	Default	Type	Description
7:0	softrst_ctr	00H	R/W	Write B0H to this register will reset all the registers to default value, the read value always keep "00H".

PACKAGE OUTLINE DIMENSIONS

WLCSP-1.55x1.55-16B

